

## **40V N-Channel Enhancement Mode MOSFET**

## **Description**

The SX160N04T uses advanced technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

 $V_{DS} = 40V I_{D} = 160A$ 

 $R_{DS(ON)}$  < 2.2m $\Omega$  @ Vgs=10V

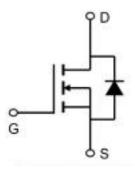
## **Application**

BMS

**BLDC** 

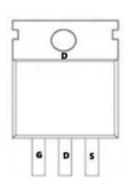
**UPS** 

ble power supply









## Absolute Maximum Ratings (Tc=25℃unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	40	V
VGS	Gate-Source Voltage	±20	V
b@Tc=25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	160	Α
lo@Tc=100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	142	А
IDM	Pulsed Drain Current <sup>2</sup>	400	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	400	mJ
IAS	Avalanche Current	40	Α
P <b>o@T</b> c=25℃	Total Power Dissipation⁴	178	W
TSTG	Storage Temperature Range	-55 to 150	$^{\circ}$
TJ	Operating Junction Temperature Range	-55 to 150	$^{\circ}$
ReJA	Thermal Resistance Junction-Ambient <sup>1</sup>	50	°C/W
ReJC	Thermal Resistance Junction-Case <sup>1</sup>	0.7	°C/W



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## **Electrical Characteristics (TJ=25℃ unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	Vgs=0V , Ip=250uA	40			V
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	Vgs=10V , ID=20A		1.6	2.2	mΩ
		Vgs=4.5V , ID=20A		2.3	3.5	
VGS(th)	Gate Threshold Voltage	Vgs=Vps , In =250uA	1.2	1.6	2.2	V
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	uA
1500		V <sub>D</sub> s=32V , V <sub>G</sub> s=0V , T <sub>J</sub> =55℃			5	
IGSS	Gate-Source Leakage Current	Vgs=±20V , Vps=0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =20A		53		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.0		Ω
Qg	Total Gate Charge (4.5V)	Vps=15V , Vgs=10V , Ip=20A		45		
Qgs	Gate-Source Charge			12		nC
Qgd	Gate-Drain Charge			18.5		
Td(on)	Turn-On Delay Time	V <sub>DD</sub> =15V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3Ω,		18.5		ns
Tr	Rise Time			9		
Td(off)	Turn-Off Delay Time	b=20A		58.5		
Tf	Fall Time			32		
Ciss	Input Capacitance			3972		
Coss	Output Capacitance	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , f=1MHz		1119		pF
Crss	Reverse Transfer Capacitance			82		
ls	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			150	Α
VsD	Diode Forward Voltage <sup>2</sup>	Vgs=0V , Is=1A , Tյ=25℃			1.2	V
		I .	1	1	1	

#### Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2 . The data tested by pulsed , pulse width  $\leq 300 \text{us}$  , duty cycle  $\leq 2\%$
- $3 \times \text{The EAS}$  data shows Max. rating . The test condition is V DD =25V,V GS =10V,L=0.5mH,I AS =40A
- $4\,{}_{\sim}$  The power dissipation is limited by  $150\,{}^{\circ}\mathrm{C}{}junction$  temperature
- $5\sqrt{100}$  The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

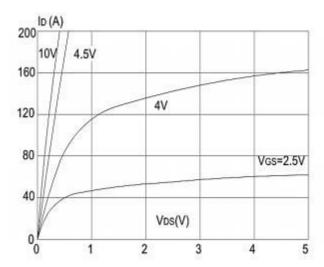
2

6 . Package limitation current is 180A

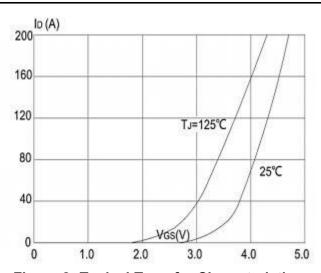


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## **Typical Characteristics**



**Figure1: Output Characteristics** 



**Figure 2: Typical Transfer Characteristics** 

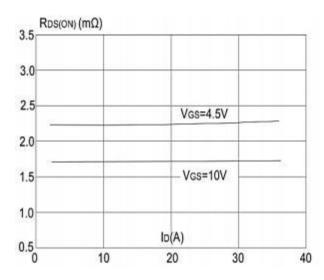
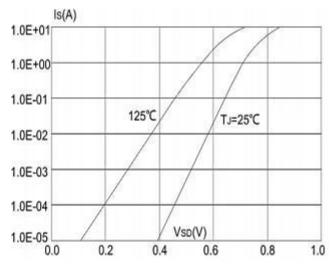
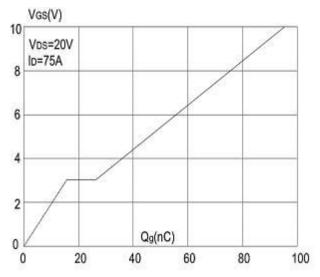


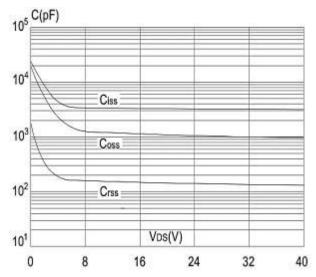
Figure 3:On-resistance vs. Drain Current



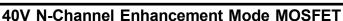
**Figure 4: Body Diode Characteristics** 



**Figure 5: Gate Charge Characteristics** 

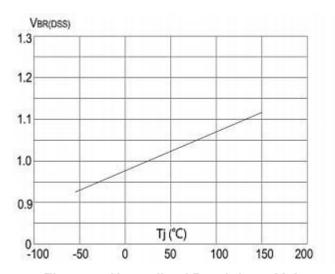


**Figure 6: Capacitance Characteristics** 





## **Typical Characteristics**



Ros(on)

2.5

2.0

1.5

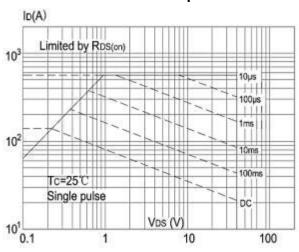
1.0

0.5

-100 -50 0 50 100 150 200

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

Figure 8: Normalized on Resistance vs Junction Temperature



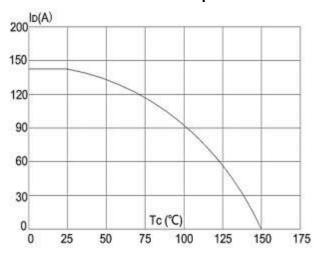


Figure 9: Maximum Safe Operating Area

Figure 10: Maximum Continuous Drain Currentvs. Case Temperature

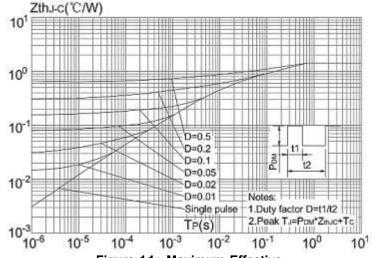
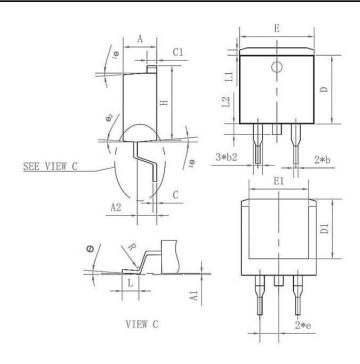


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Cas



# **MOSFET Package Mechanical Data-TO-263-3L**



		Common		
Symbol	mm			
	Mim	Nom	Max	
Α	4.35	4.47	4.60	
A1	0.09	0.10	0.11	
A2	2.30	2.40	2.70	
b	0.70	0.80	1.00	
b2	1.25	1.36	1.50	
С	0.45	0.50	0.65	
C1	1.29	1.30	9.40	
D	9.10	9.20	9.30	
D1	7.90	8.00	8.10	
E	9.85	10.00	10.20	
E1	7.90	8.00	8.10	
Н	15.30	15.50	15.70	
е	-	2.54	-	
L	2.34	2.54	2.74	
L1	1.00	1.10	1.20	
L2	1.30	1.40	1.50	
R	0.24	0.25	0.26	
θ	0°	4°	8°	
Θ1	4°	7°	10°	
Θ2	0°	3°	6°	

## **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-263-3L		800

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